

# MICROTECH 2018

## THE ANNUAL CONFERENCE OF IMAPS-UK



## MOORE THAN PACKAGING: 50 YEARS GONE; 50 YEARS ON!

IMAPS-UK Annual Conference, 9 – 10 April 2018

Windsor Conference Building, Royal Holloway, London University, Egham TW20 0EX

JUST OFF THE M25, CLOSE TO HEATHROW

## CALL FOR ABSTRACTS

MicroTech 2018 continues a series of successful IMAPS-UK annual conferences. 2018 marks the 50th anniversary for IMAPS-UK. A reason to celebrate and a conference venue in close proximity to one of the UK's premier airports ensures ease of access for many attendees from across the world.

The conference and adjoining exhibition bring together the entire microelectronics supply chain and is the only UK event dedicated to micro-assembly, packaging and related technologies.

All who wish to present their work at this event are invited to submit an abstract by Fri 8<sup>th</sup> Dec 2017.

### Organizing Committee

Event Chair  
Peter Barnwell

Exhibition Co-Chair  
Scott Wood  
Accelonix

General Co-Chair  
Chris Powley  
Manufacturing Technology Centre

Technical Co-Chair  
Martin Wickham  
National Physical Laboratory

Technical Co-Chair  
John Lipp  
Science and Technology Facilities Council

Academic Co-Chair  
Gerard Cummins  
Herriot Watt University

## Instructions for participation

We invite submission of abstracts in the following areas:

- **Research Papers:** These will describe high-impact academic research relating to the conference topics.
- **Technical Presentations:** Technical presentations showcasing in-production or pre-production techniques relating to the conference topics.
- **Current/Future trends:** Presentations demonstrating how markets related to the main conference topics are developing over time.

All abstracts received by the submission deadline will be evaluated by the technical committee. Abstracts covering a balanced range of the main conference topics will be selected and invited to provide an oral presentation (25mins + 5mins questions) or poster presentation (A0 size) during the conference. Some posters presenters may also be invited to provide a brief oral presentation showcasing their poster content to the full audience.

## Conference topics

Process and Technologies	Materials	Applications and trends	Future directions, challenges and technologies
<ul style="list-style-type: none"> <li>• Embedded Packaging</li> <li>• Additive Electronics Manufacturing</li> <li>• Industry 4.0</li> <li>• Reliability</li> <li>• Wafer level packaging</li> </ul>	<ul style="list-style-type: none"> <li>• Substrate materials</li> <li>• Polymers for micro-electronics</li> <li>• Novel materials</li> <li>• Compound semiconductor</li> <li>• High temperature materials</li> <li>• Thermal management</li> </ul>	<ul style="list-style-type: none"> <li>• Quantum computing</li> <li>• LED arrays</li> <li>• Sensor arrays</li> <li>• Environmental monitoring</li> <li>• High reliability</li> <li>• Telecoms</li> <li>• Commercial/consumer</li> <li>• Automotive</li> <li>• Rail</li> </ul>	<ul style="list-style-type: none"> <li>• System integration</li> <li>• Power density</li> <li>• Optical connections</li> <li>• Environmental impact</li> <li>• Emerging packaging technologies</li> </ul>

Those wishing to present their work at MicroTech2018 must submit a 200-300 word abstract electronically to: [secretariat@imaps.org.uk](mailto:secretariat@imaps.org.uk).

### Deadlines

Abstract submission (200-300 words)	Fri 8 <sup>th</sup> Dec 2017
Confirmed speaker biographies and photographs	Fri 26 <sup>th</sup> Jan 2018
Final slide set or poster graphics (ppt or pdf)	Fri 30 <sup>th</sup> Mar 2018

